

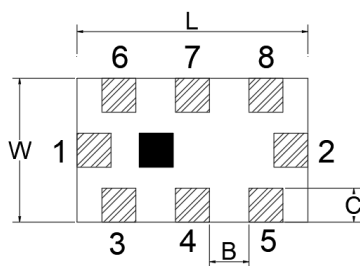
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

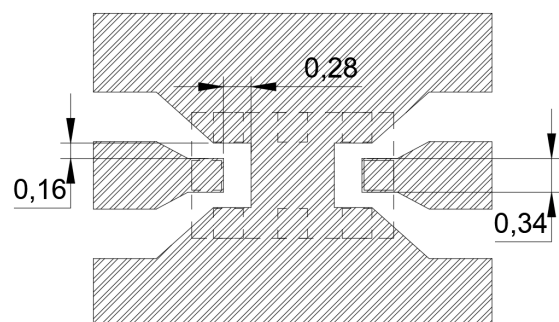
NO.	Parameter	Frequency	SPC		
			MIN	Typ	Max.
1	Insertion Loss (dB)@25℃	DC~1000 MHz	-	0.8	1.8
		1370 MHz	-	3.0	-
2	Attenuation (dB)	1550~1900MHz	20	30	-
		1900~3000MHz	35	45	-
		3000~6000MHz	30	35	-
		6000~10000MHz	-	30	-
3	VSWR	DC~1370 MHz	-	-	1.8
4	In/Output Impedance (Ω)	50			
5	Power(W)	5.5 Max.			
Operating & Storage Condition (Component) Operation Temperature Range: -55℃ ~ +125℃ Storage Temperature Range: -55℃~ +125℃					
Storage Condition before Soldering (Included packaging material) Storage Temperature Range: +5 ~ +40 ℃ Humidity: 30 to 70% relative humidity					

Construction

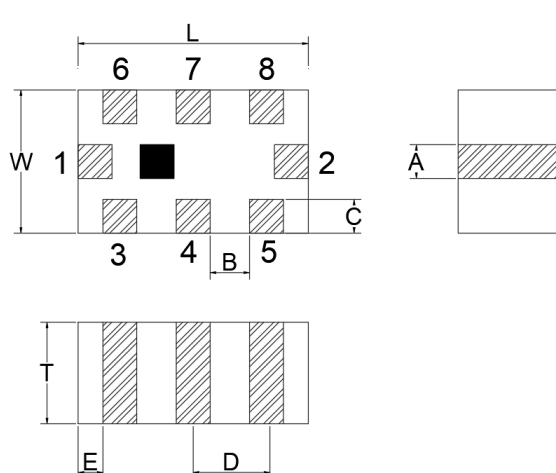


PIN	Connection	PIN	Connection
1	input Port	2	output Port
3	GND	4	GND
5	GND	6	GND
7	GND	8	GND

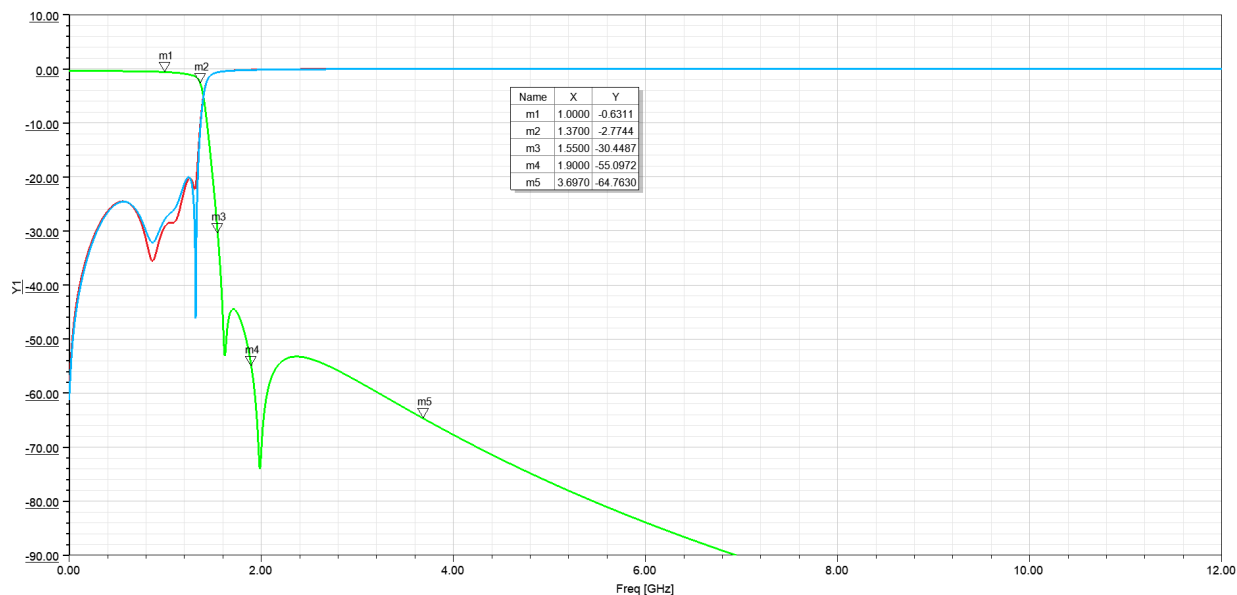
Mounting Considerations



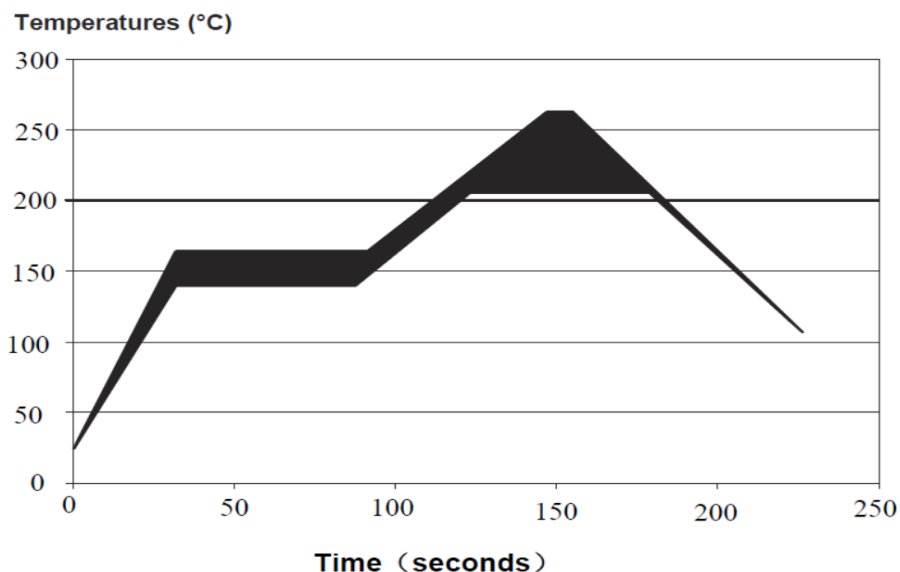
Dimensions

Figure	Symbol	Dimension (mm)
	L	2.00 ± 0.20
	W	1.25 ± 0.20
	T	0.95 ± 0.20
	A	0.30 ± 0.15
	B	0.35 ± 0.15
	C	0.30 ± 0.15
	D	0.65 ± 0.15
	E	0.20 ± 0.15

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.